

74LVC16245A; 74LVCH16245A

16-bit bus transceiver with direction pin; 5 V tolerant; 3-state

Rev. 12 — 13 February 2012

Product data sheet

1. General description

The 74LVC16245A; 74LVCH16245A are 16-bit transceivers featuring non-inverting 3-state bus compatible outputs in both send and receive directions. The device features two output enable ($\overline{\text{nOE}}$) inputs for easy cascading and two send/receive ($\overline{\text{nDIR}}$) inputs for direction control. $\overline{\text{nOE}}$ controls the outputs so that the buses are effectively isolated. This device can be used as two 8-bit transceivers or one 16-bit transceiver.

Inputs can be driven from either 3.3 V or 5 V devices. When disabled, up to 5.5 V can be applied to the outputs. These features allow the use of these devices in mixed 3.3 V and 5 V applications.

The 74LVCH16245A bus hold on data inputs eliminates the need for external pull-up resistors to hold unused inputs.

2. Features and benefits

- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low power consumption
- MULTIBYTE flow-through standard pin-out architecture
- Low inductance multiple power and ground pins for minimum noise and ground bounce
- Direct interface with TTL levels
- High-impedance when $V_{CC} = 0$ V
- All data inputs have bus hold (74LVCH16245A only)
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-B exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from -40 °C to $+85$ °C and -40 °C to $+125$ °C



3. Ordering information

Table 1. Ordering information

Type number	Temperature range	Package		
		Name	Description	Version
74LVC16245ADL 74LVCH16245ADL	–40 °C to +125 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	SOT370-1
74LVC16245ADGG 74LVCH16245ADGG	–40 °C to +125 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1
74LVC16245AEV 74LVCH16245AEV	–40 °C to +125 °C	VFBGA56	plastic very thin fine-pitch ball grid array package; 56 balls; body 4.5 × 7 × 0.65 mm	SOT702-1
74LVC16245ABX 74LVCH16245ABX	–40 °C to +125 °C	HXQFN60	plastic compatible thermal enhanced extremely thin quad flat package; no leads; 60 terminals; body 4 × 6 × 0.5 mm	SOT1134-2

4. Functional diagram

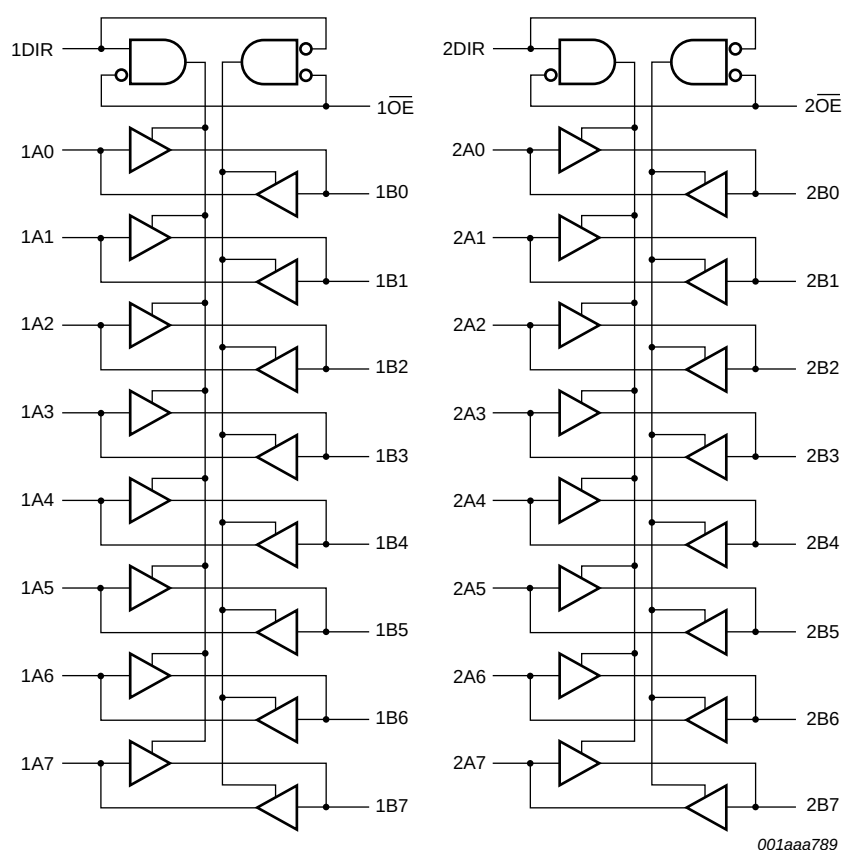


Fig 1. Logic symbol

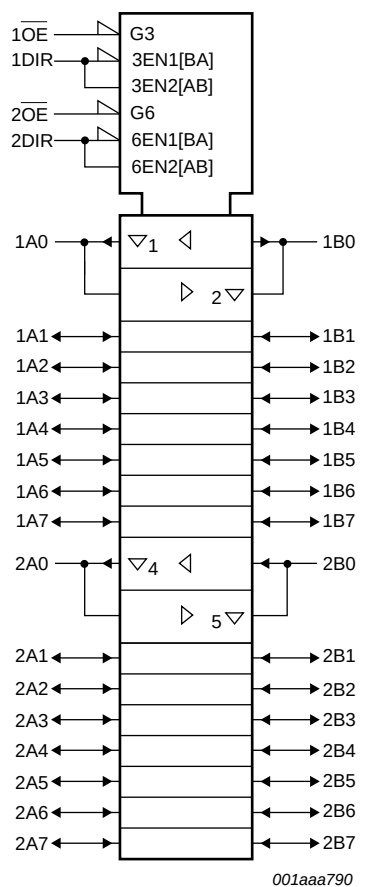


Fig 2. IEC logic symbol

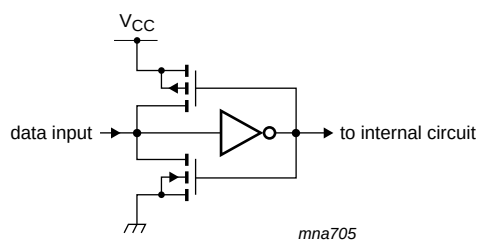
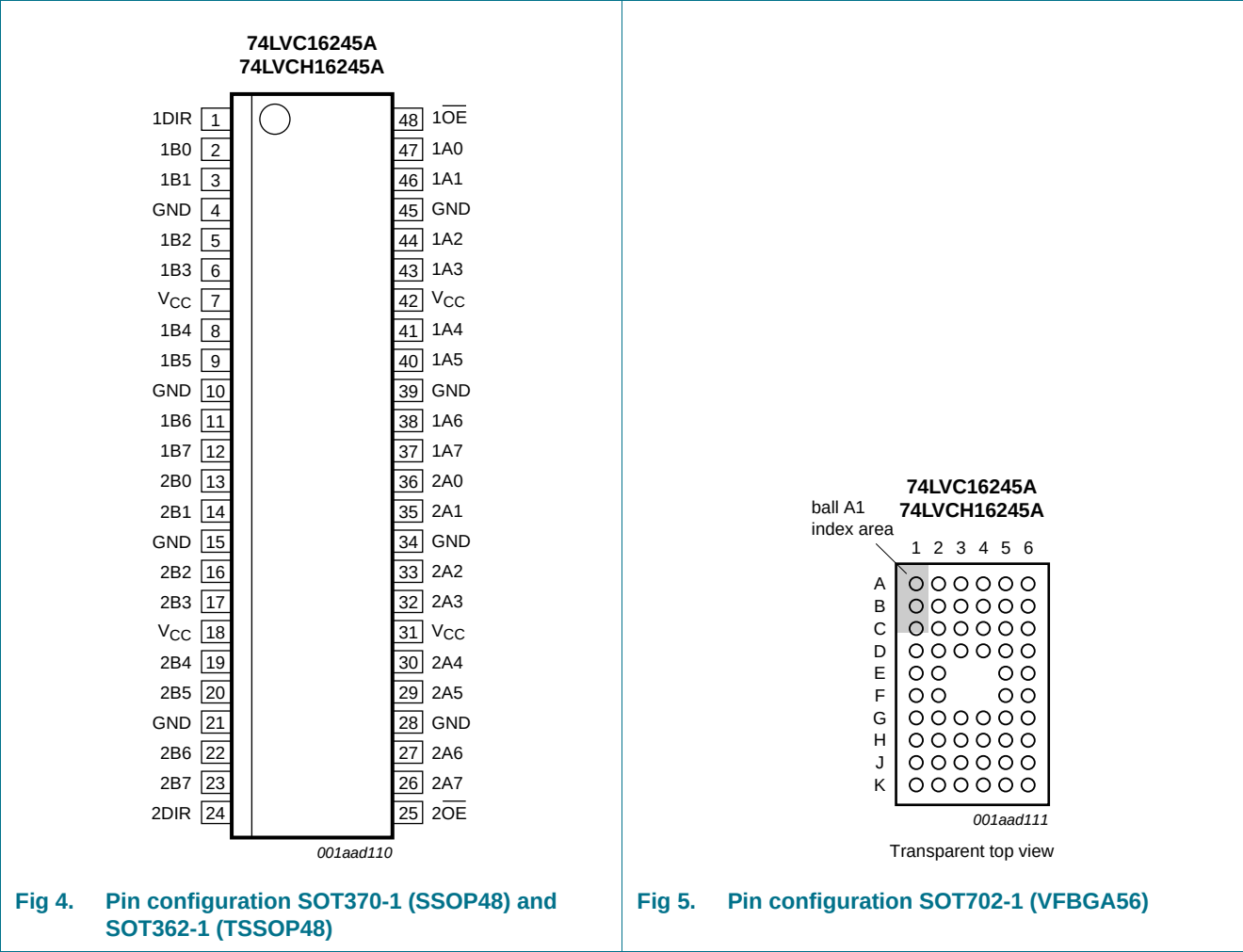
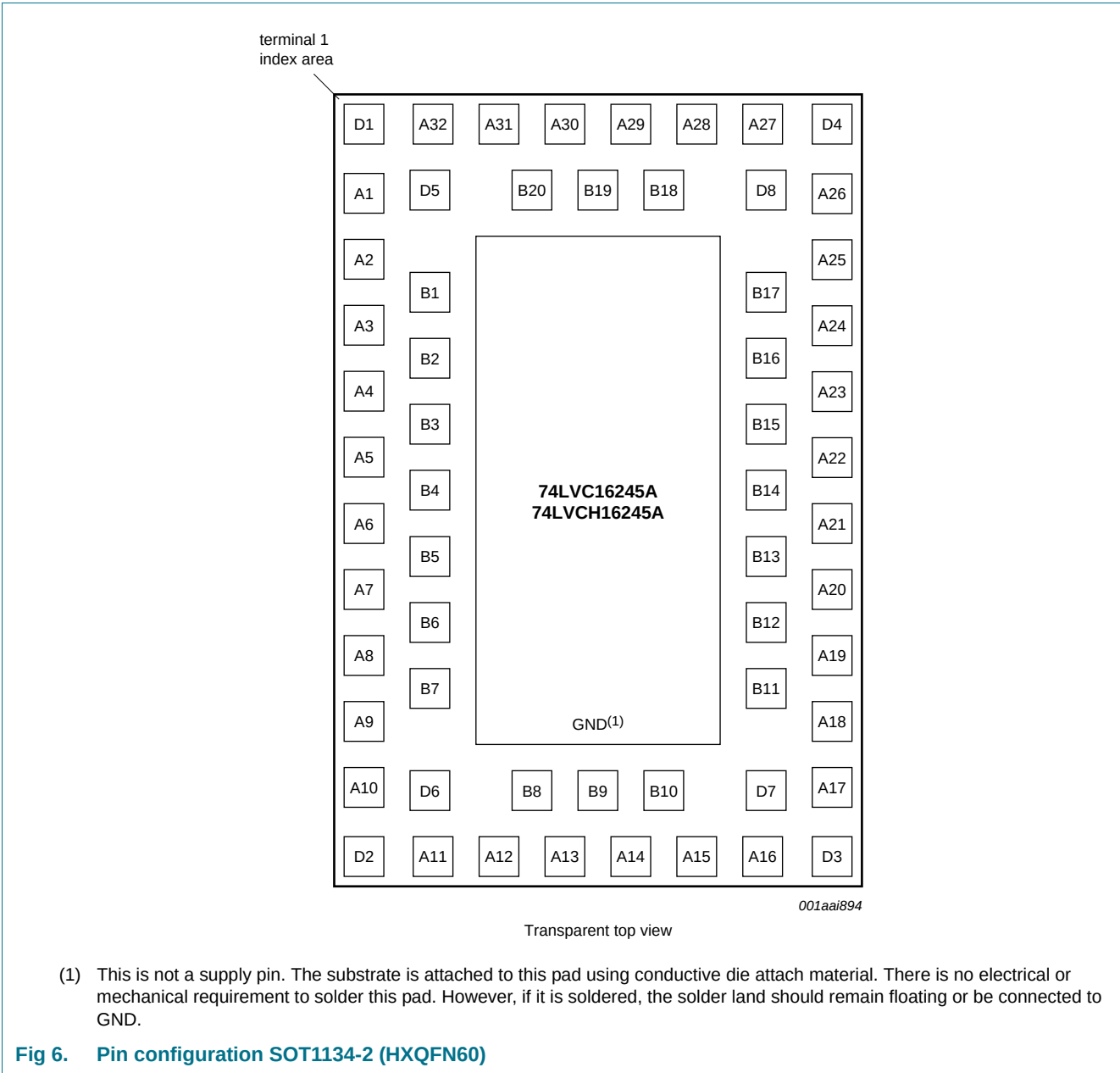


Fig 3. Bus hold circuit

5. Pinning information

5.1 Pinning





5.2 Pin description

Table 2. Pin description

Symbol	Pin			Description
	SOT370-1 and SOT362-1	SOT702-1	SOT1134-2	
1DIR, 2DIR	1, 24	A1, K1	A30, A13	direction control input
1B0 to 1B7	2, 3, 5, 6, 8, 9, 11, 12	B2, B1, C2, C1, D2, D1, E2, E1	B20, A31, D5, D1, A2, B2, B3, A5	data input/output
2B0 to 2B7	13, 14, 16, 17, 19, 20, 22, 23	F1, F2, G1, G2, H1, H2, J1, J2	A6, B5, B6, A9, D2, D6, A12, B8	data input/output
GND	4, 10, 15, 21, 28, 34, 39, 45	B3, B4, D3, D4, G3, G4, J3, J4	A32, A3, A8, A11, A16, A19, A24, A27	ground (0 V)
V _{CC}	7, 18, 31, 42	C3, C4, H3, H4	A1, A10, A17, A26	supply voltage
$\overline{1OE}$, $\overline{2OE}$	48, 25	A6, K6	A29, A14	output enable input (active LOW)
1A0 to 1A7	47, 46, 44, 43, 41, 40, 38, 37	B5, B6, C5, C6, D5, D6, E5, E6	B18, A28, D8, D4, A25, B16, B15, A22	data input/output
2A0 to 2A7	36, 35, 33, 32, 30, 29, 27, 26	F6, F5, G6, G5, H6, H5, J6, J5	A21, B13, B12, A18, D3, D7, A15, B10	data input/output
n.c.	-	A2, A3, A4, A5, K2, K3, K4, K5	A4, A7, A20, A23, B1, B4, B7, B9, B11, B14, B17, B19	not connected

6. Functional description

Table 3. Function table^[1]

Inputs		Outputs	
$\overline{nOE}$	nDIR	nAn	nBn
L	L	nAn = nBn	inputs
L	H	inputs	nBn = nAn
H	X	Z	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
V_I	input voltage		[1] -0.5	+6.5	V
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	± 50	mA
V_O	output voltage	output HIGH or LOW	[2] -0.5	$V_{CC} + 0.5$	V
		output 3-state	[2] -0.5	+6.5	V
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 50	mA
I_{CC}	supply current		-	100	mA
I_{GND}	ground current		-100	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C;			
		(T)SSOP48 package	[3] -	500	mW
		VFBGA56 package	[4] -	1000	mW
		HXQFN60 package	[4] -	1000	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] Above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.

[4] Above 70 °C the value of P_{tot} derates linearly with 1.8 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	3.6	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage	output HIGH or LOW	0	-	V_{CC}	V
		output 3-state	0	-	5.5	V
T_{amb}	ambient temperature	in free air	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.2$ V to 2.7 V	0	-	20	ns/V
		$V_{CC} = 2.7$ V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 1.2 V	1.08	-	-	1.08	-	V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	0.65 × V _{CC}	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.2 V	-	-	0.12	-	0.12	V
		V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = –100 µA; V _{CC} = 1.65 V to 3.6 V	V _{CC} – 0.2	-	-	V _{CC} – 0.3	-	V
		I _O = –4 mA; V _{CC} = 1.65 V	1.2	-	-	1.05	-	V
		I _O = –8 mA; V _{CC} = 2.3 V	1.8	-	-	1.65	-	V
		I _O = –12 mA; V _{CC} = 2.7 V	2.2	-	-	2.05	-	V
		I _O = –18 mA; V _{CC} = 3.0 V	2.4	-	-	2.25	-	V
		I _O = –24 mA; V _{CC} = 3.0 V	2.2	-	-	2.0	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = 100 µA; V _{CC} = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	-	0.45	-	0.65	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	-	0.6	-	0.8	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	-	0.4	-	0.6	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	-	0.55	-	0.8	V
I _I	input leakage current ^[2]	V _I = 5.5 V or GND; V _{CC} = 3.6 V	-	±0.1	±5	-	±20	µA
I _{OZ}	OFF-state output current ^{[2][3]}	V _I = V _{IH} or V _{IL} ; V _O = 5.5 V or GND; V _{CC} = 3.6 V	-	±0.1	±5	-	±20	µA
I _{OFF}	power-off leakage current	V _I or V _O = 5.5 V; V _{CC} = 0.0 V	-	±0.1	±10	-	±20	µA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 3.6 V	-	0.1	20	-	80	µA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} – 0.6 V; I _O = 0 A; V _{CC} = 2.7 V to 3.6 V	-	5	500	-	5000	µA
C _I	input capacitance	V _{CC} = 0 V to 3.6 V; V _I = GND to V _{CC}	-	5.0	-	-	-	pF
C _{I/O}	input/output capacitance	V _{CC} = 0 V to 3.6 V; V _I = GND to V _{CC}	-	10	-	-	-	pF

Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
I _{BHL}	bus hold LOW current ^{[4][5]}	V _{CC} = 1.65 V; V _I = 0.58 V	10	-	-	10	-	μA
		V _{CC} = 2.3 V; V _I = 0.7 V	30	-	-	25	-	μA
		V _{CC} = 3.0 V; V _I = 0.8 V	75	-	-	60	-	μA
I _{BHH}	bus hold HIGH current ^{[4][5]}	V _{CC} = 1.65 V; V _I = 1.07 V	–10	-	-	–10	-	μA
		V _{CC} = 2.3 V; V _I = 1.7 V	–30	-	-	–25	-	μA
		V _{CC} = 3.0 V; V _I = 2.0 V	–75	-	-	–60	-	μA
I _{BHLO}	bus hold LOW overdrive current ^{[4][6]}	V _{CC} = 1.95 V	200	-	-	200	-	μA
		V _{CC} = 2.7 V	300	-	-	300	-	μA
		V _{CC} = 3.6 V	500	-	-	500	-	μA
I _{BHHO}	bus hold HIGH overdrive current ^{[4][6]}	V _{CC} = 1.95 V	–200	-	-	–200	-	μA
		V _{CC} = 2.7 V	–300	-	-	–300	-	μA
		V _{CC} = 3.6 V	–500	-	-	–500	-	μA

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.[2] The bus hold circuit is switched off when V_I > V_{CC} allowing 5.5 V on the input terminal.[3] For I/O ports the parameter I_{OZ} includes the input leakage current.

[4] Valid for data inputs of bus hold parts only (74LVCH16245A). Note that control inputs do not have a bus hold circuit.

[5] The specified sustaining current at the data input holds the input below the specified V_I level.

[6] The specified overdrive current at the data input forces the data input to the opposite input state.

10. Dynamic characteristics

Table 7. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V). For test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[2]	Max	Min	Max	
t _{pd}	propagation delay	nAn to nBn; nBn to nAn; see Figure 7 ^[1]						
		V _{CC} = 1.2 V	-	13.0	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	1.5	5.2	12.2	1.5	13.8	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.8	6.0	1.0	6.7	ns
		V _{CC} = 2.7 V	1.0	2.7	4.7	1.0	6.0	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.4	4.5	1.0	6.0	ns
t _{en}	enable time	nOE to nAn, nBn; see Figure 8 ^[1]						
		V _{CC} = 1.2 V	-	15.0	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	1.5	5.9	15.0	1.5	16.9	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	3.3	7.9	1.0	8.8	ns
		V _{CC} = 2.7 V	1.5	3.5	6.7	1.5	8.5	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.7	5.5	1.0	7.0	ns

Table 7. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[2]	Max	Min	Max	
t_{dis}	disable time	nOE to nAn, nBn; see Figure 8 ^[1]						
		$V_{CC} = 1.2\text{ V}$	-	11.0	-	-	-	ns
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.0	4.9	13.1	1.0	14.7	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.5	2.7	7.1	0.5	7.9	ns
		$V_{CC} = 2.7\text{ V}$	1.5	3.4	6.6	1.5	8.5	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	1.5	3.3	5.6	1.5	7.0	ns
C_{PD}	power dissipation capacitance	per input; $V_I = \text{GND to } V_{CC}$ ^[3]						
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	11.5	-	-	-	pF
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	15.2	-	-	-	pF
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	18.5	-	-	-	pF

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

t_{en} is the same as t_{PZL} and t_{PZH} .

t_{dis} is the same as t_{PLZ} and t_{PHZ} .

[2] Typical values are measured at $T_{amb} = 25\text{ °C}$ and $V_{CC} = 1.2\text{ V}, 1.8\text{ V}, 2.5\text{ V}, 2.7\text{ V}$ and 3.3 V respectively.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz; f_o = output frequency in MHz

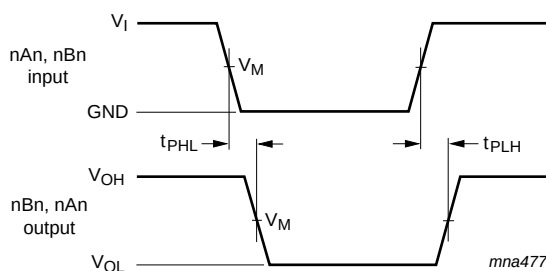
C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

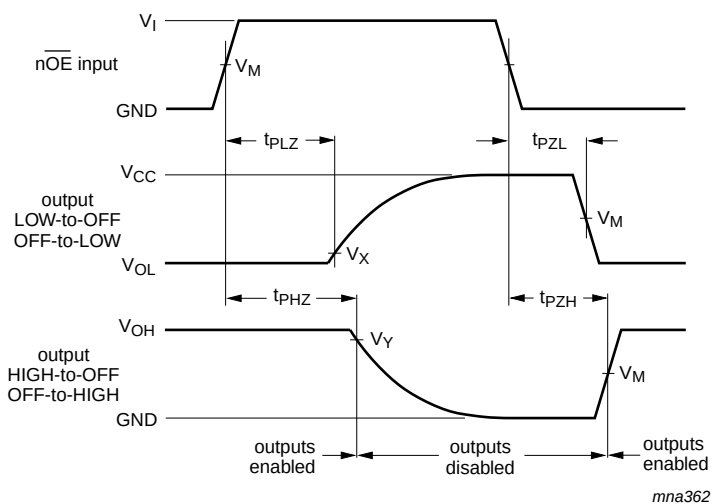
11. Waveforms



Measurement points are given in [Table 8](#).

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. The input (nAn, nBn) to output (nBn, nAn) propagation delays



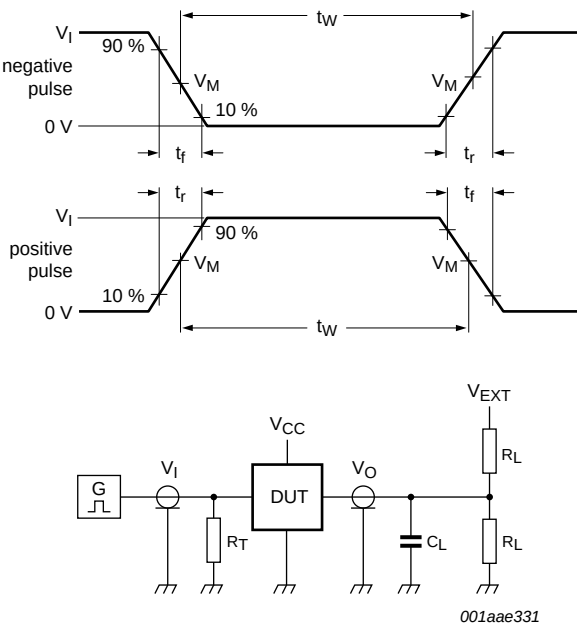
Measurement points are given in [Table 8](#).

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 8. 3-state enable and disable times

Table 8. Measurement points

Supply voltage	V_M	Input			
V_{CC}		V_I	$t_r = t_f$	V_X	V_Y
1.2 V	$0.5 \times V_{CC}$	V_{CC}	$\leq 2.5 \text{ ns}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	V_{CC}	$\leq 2.5 \text{ ns}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	V_{CC}	$\leq 2.5 \text{ ns}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.7 V	1.5 V	2.7 V	$\leq 2.5 \text{ ns}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
3.0 V to 3.6 V	1.5 V	2.7 V	$\leq 2.5 \text{ ns}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$



Test data is given in [Table 9](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 9. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
1.2 V	V_{CC}	≤ 2 ns	30 pF	1 k Ω	open	$2 \times V_{CC}$	GND
1.65 V to 1.95 V	V_{CC}	≤ 2 ns	30 pF	1 k Ω	open	$2 \times V_{CC}$	GND
2.3 V to 2.7 V	V_{CC}	≤ 2 ns	30 pF	500 Ω	open	$2 \times V_{CC}$	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	$2 \times V_{CC}$	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	$2 \times V_{CC}$	GND

12. Package outline

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

SOT370-1

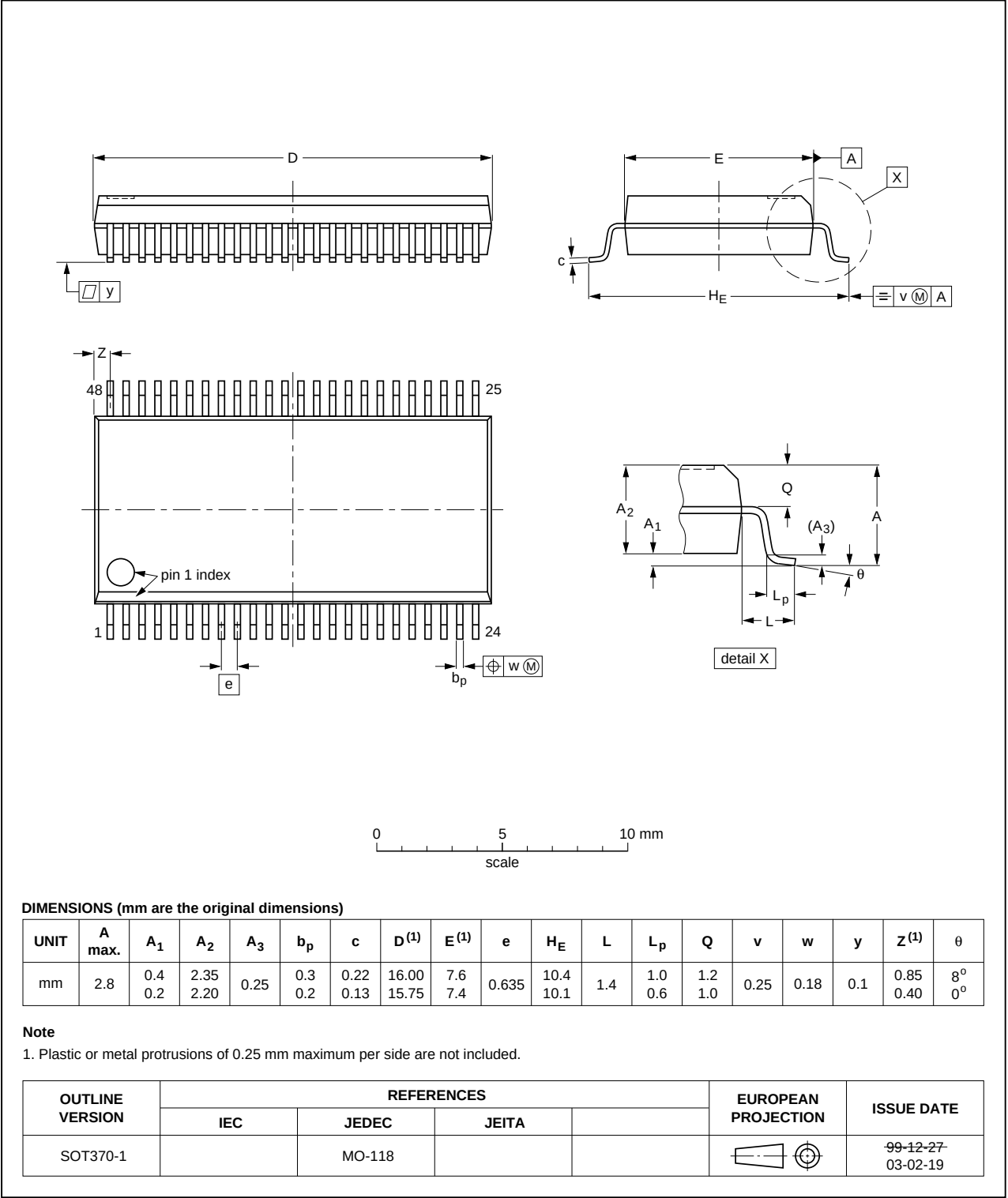


Fig 10. Package outline SOT370-1 (SSOP48)

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1

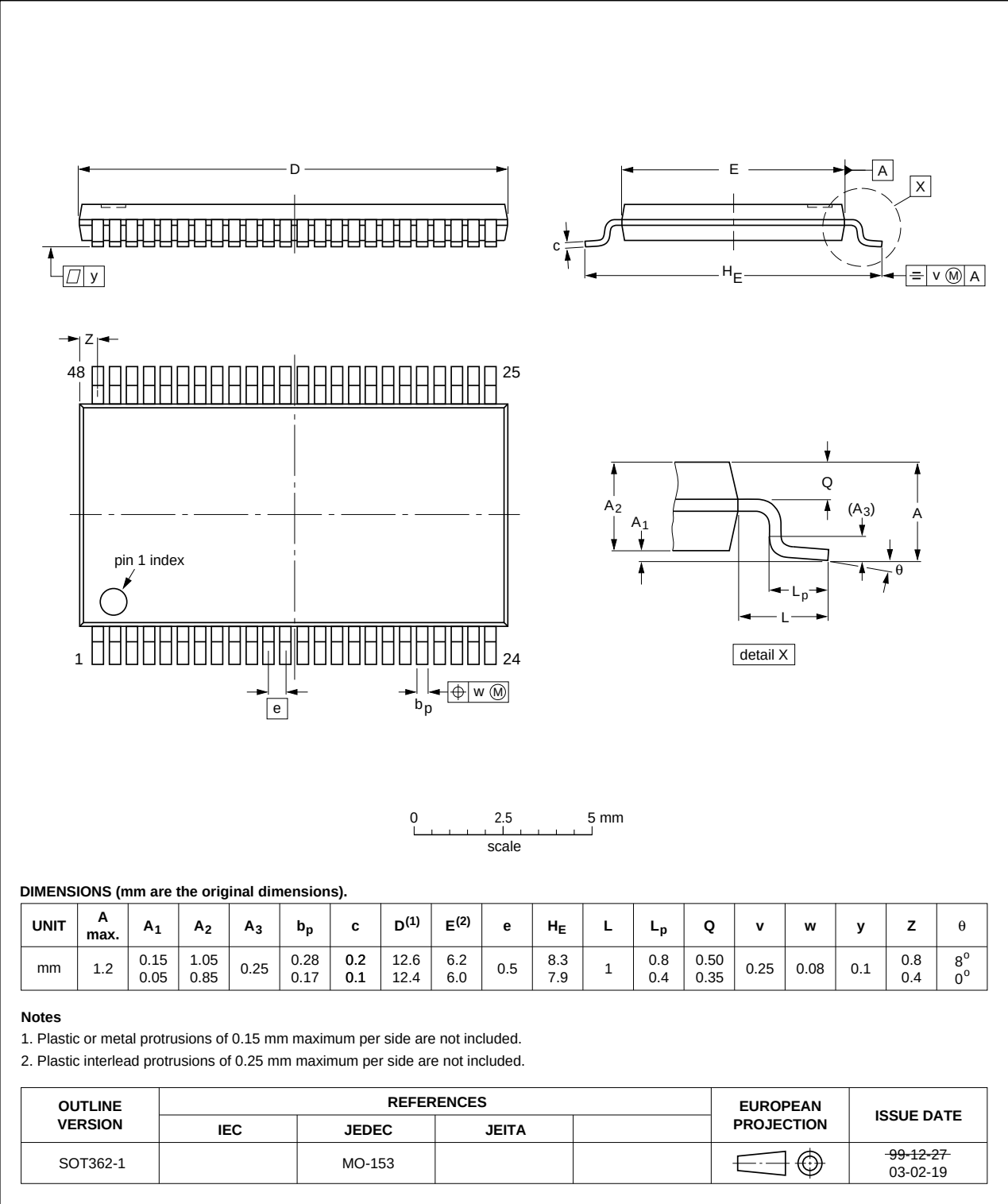


Fig 11. Package outline SOT362-1 (TSSOP48)

VFBGA56: plastic very thin fine-pitch ball grid array package; 56 balls; body 4.5 x 7 x 0.65 mm

SOT702-1

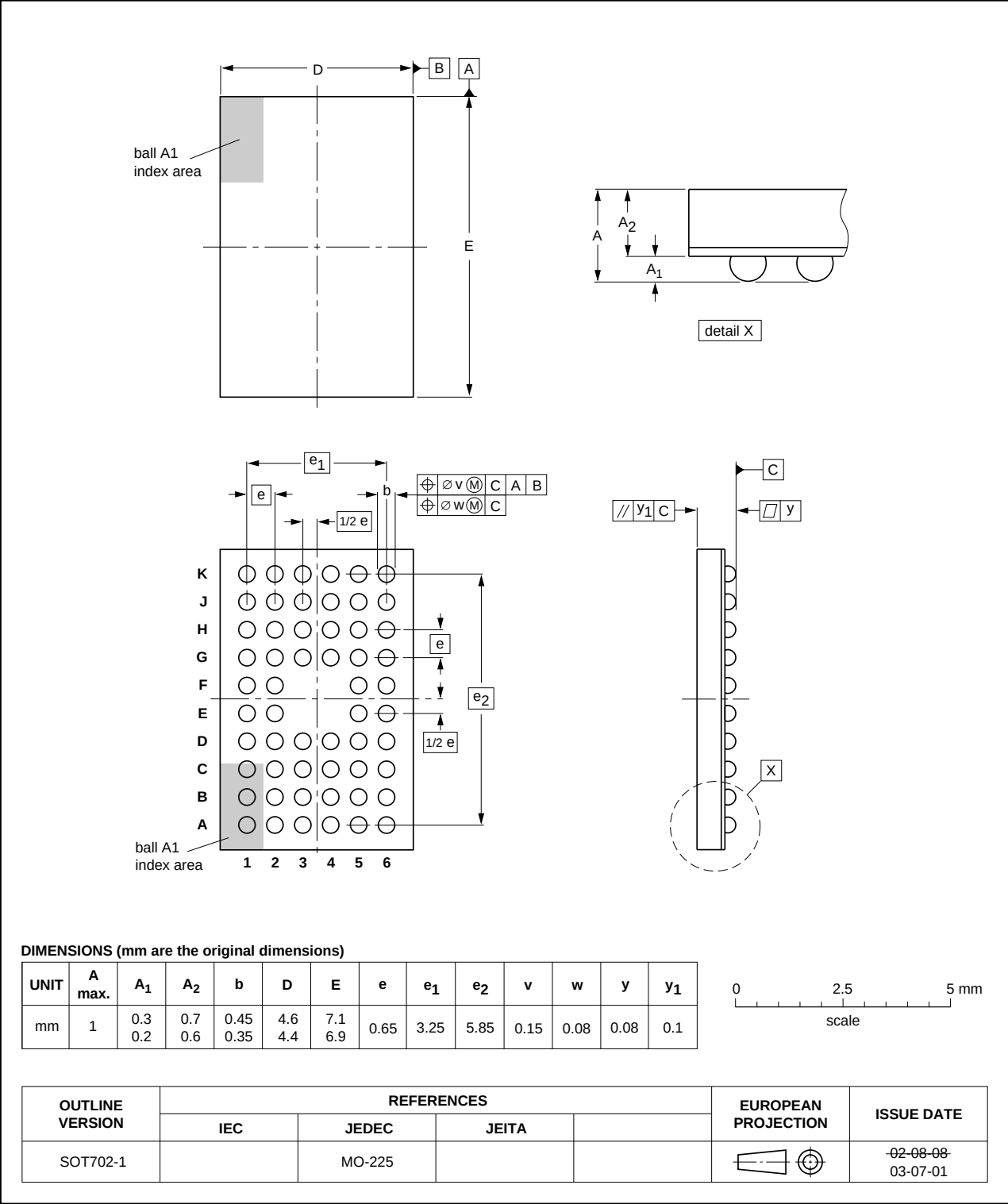


Fig 12. Package outline SOT702-1 (VFBGA56)

HXQFN60: plastic compatible thermal enhanced extremely thin quad flat package; no leads;
 60 terminals; body 4 x 6 x 0.5 mm

SOT1134-2

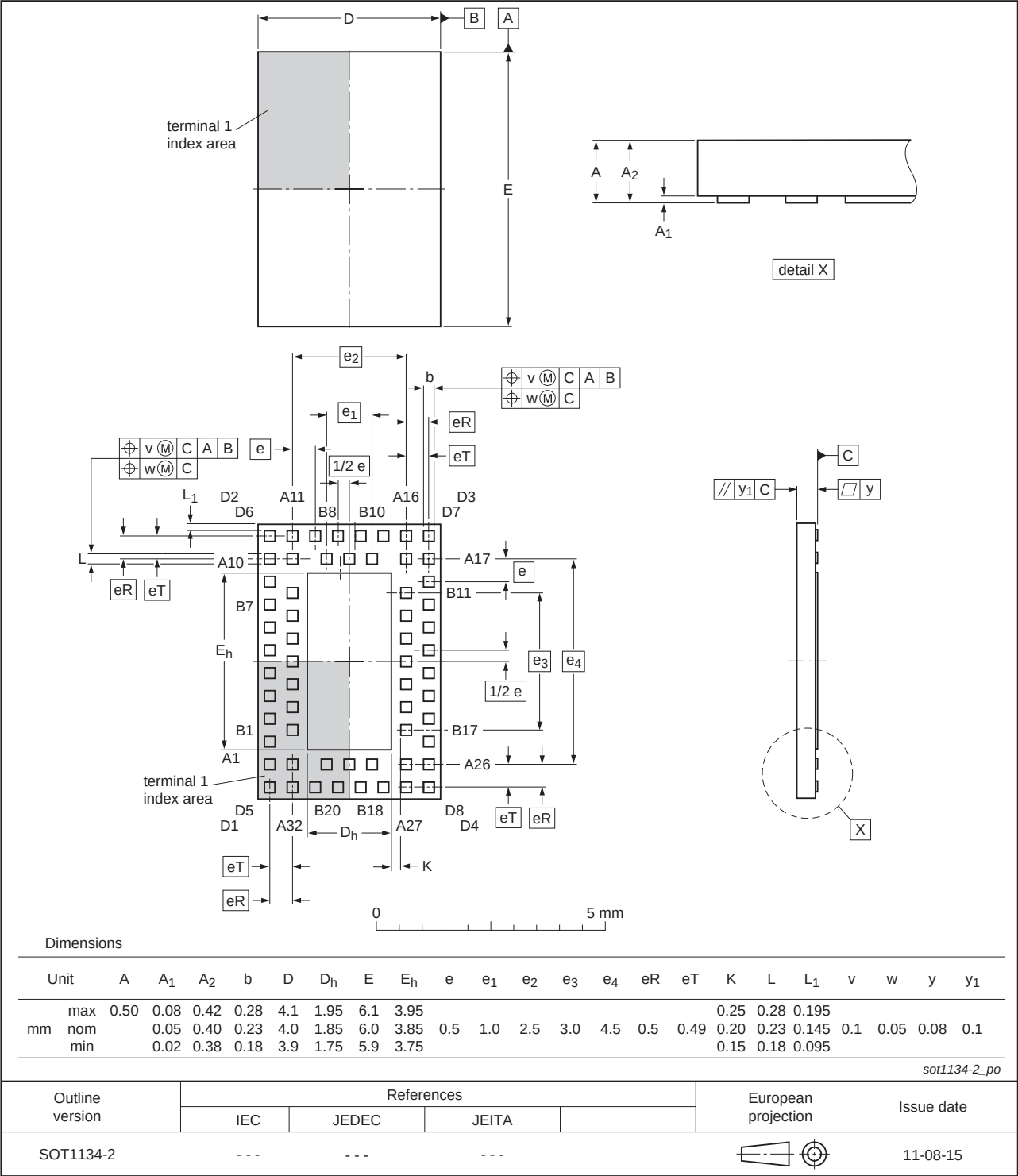


Fig 13. Package outline SOT1134-2 (HXQFN60)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC_LVCH16245A v.12	20120213	Product data sheet	-	74LVC_LVCH16245A v.11
Modifications:	For type number 74LVC16245ABX and 74LVCH16245ABX the sot code has changed to SOT1134-2.			
74LVC_LVCH16245A v.11	20111208	Product data sheet	-	74LVC_LVCH16245A v.10
Modifications:	Table 4, Table 5, Table 6, Table 7, and Table 9: values added for lower voltage ranges.			
74LVC_LVCH16245A v.10	20110623	Product data sheet	-	74LVC_LVCH16245A v.9
Modifications:	- type numbers 74LVC16245ABQ and 74LVCH16245ABQ changed to 74LVC16245ABX and 74LVCH16245ABX. Figure 6: figure note 1 changed.			
74LVC_LVCH16245A v.9	20100329	Product data sheet	-	74LVC_LVCH16245A v.8
74LVC_LVCH16245A v.8	20081106	Product data sheet	-	74LVC_LVCH16245A v.7
74LVC_LVCH16245A v.7	20031125	Product specification	-	74LVC_LVCH16245A v.6
74LVC_LVCH16245A v.6	20030130	Product specification	-	74LVC_LVCH16245A v.5
74LVC_LVCH16245A v.5	20021030	Product specification	-	74LVC_H16245A v.4
74LVC_H16245A v.4	19970925	Product specification	-	74LVC16245A_74LVCH16245A v.3
74LVC16245A_74LVCH16245A v.3	19970925	Product specification	-	74LVC16245A v.2
74LVC16245A v.2	19970801	Product specification	-	74LVC16245A v.1
74LVC16245A v.1	-	-	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 13 February 2012

Document identifier: 74LVC_LVCH16245A